

KHX1866C9S3K2/4GX

4GB (2GB 256M x 64-Bit x 2 pcs.) DDR3-1866MHz

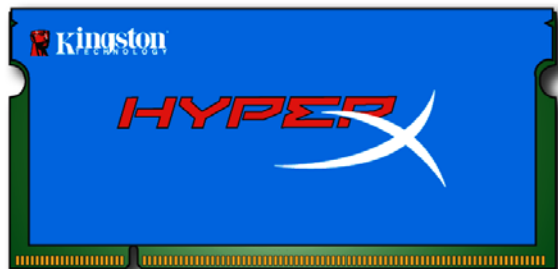
CL9 204-Pin SODIMM Kit

DESCRIPTION:

Kingston's KHX1866C9S3K2/4GX is a kit of two 256M x 64-bit (2GB) DDR3-1866MHz CL9 SDRAM (Synchronous DRAM) memory modules, based on sixteen 128M x 8-bit DDR3 FBGA components per module. Total kit capacity is 4GB. Each module kit has been tested to run at DDR3-1866MHz at a low latency timing of 9-9-9-27-2T at 1.5V. The SPDs are programmed to JEDEC standard latency DDR3-1333MHz timing of 9-9-9 at 1.5V. Each 204-pin SODIMM uses gold contact fingers and requires +1.5V. The JEDEC standard electrical and mechanical specifications are as follows:

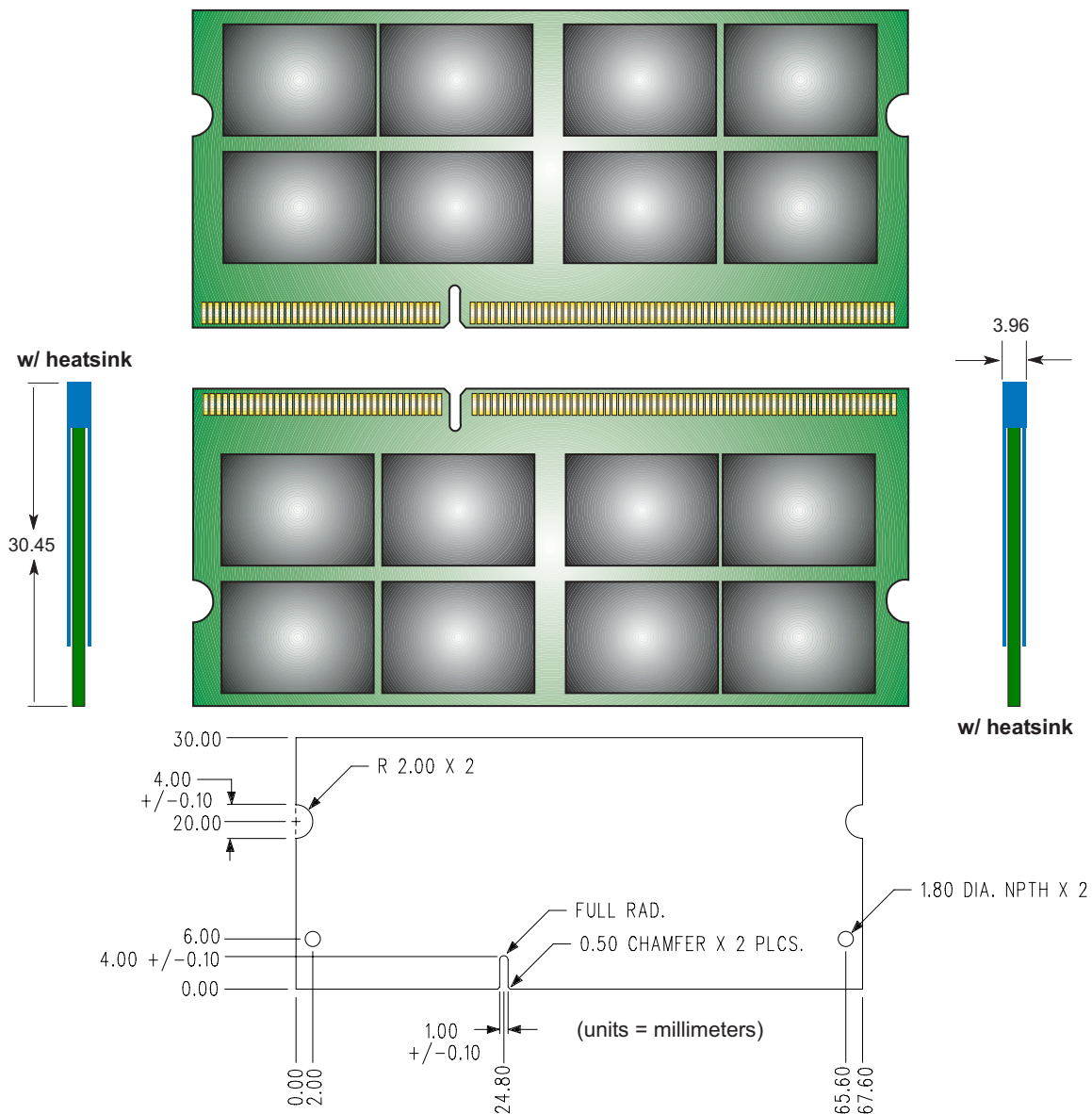
FEATURES:

- ✓ JEDEC standard 1.5V \pm 0.075V Power Supply
- ✓ VDDQ = 1.5V \pm 0.075V
- ✓ 667MHz fCK for 1333Mb/sec/pin
- ✓ 8 independent internal bank
- ✓ Programmable CAS Latency: 5,6,7,8,9,10
- ✓ Posted CAS
- ✓ Programmable Additive Latency: 0, CL - 2, or CL - 1 clock
- ✓ Programmable CAS Write Latency(CWL) = 7(DDR3-1333)
- ✓ 8-bit pre-fetch
- ✓ Burst Length: 8 (Interleave without any limit, sequential with starting address "000" only), 4 with tCCD = 4 which does not allow seamless read or write [either on the fly using A12 or MRS]
- ✓ Bi-directional Differential Data Strobe
- ✓ Internal(self) calibration : Internal self calibration through ZQ pin (RZQ : 240 ohm \pm 1%)
- ✓ On Die Termination using ODT pin
- ✓ Average Refresh Period 7.8us at lower then TCASE 85°C, 3.9us at 85°C < TCASE . 95°C
- ✓ Asynchronous Reset
- ✓ PCB : Height 1.180" (30.00mm), double sided component



PERFORMANCE:

- | | |
|--|--------------------------------|
| ✓ CL(IDD) | 9 cycles |
| ✓ Row Cycle Time (tRCmin) | 49.5ns (min.) |
| ✓ Refresh to Active/Refresh Command Time (tRFCmin) | 110ns |
| ✓ Row Active Time (tRASmin) | 36ns (min.) |
| ✓ Power | 1.125 W (operating per module) |
| ✓ UL Rating | 94 V - 0 |
| ✓ Operating Temperature | 0° C to 85° C |
| ✓ Storage Temperature | -55° C to +100° C |

MODULE DIMENSIONS:**w/ Heatsink Assembly**